

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims 1-13:**

1. (previously presented) An etching method in which two or more disk-shaped members immersed into an etching solution are held in a state where plate surfaces of the members face each other, and etching is conducted while rotating the members,  
Wherein a non-rotating member is disposed between the members.
2. (original) The etching method according to claim 1, wherein the non-rotating member has a substantially disk shape.
3. (previously presented) The etching method according to claim 1,  
wherein the surface area of the non-rotating member is 95-105% of the surface area of the members.
4. (currently amended) The etching method according to claim 1, wherein the disk-shaped members are semiconductor wafers.
5. (currently amended) An etching apparatus comprising:  
an etching chamber filled with an etching solution; and  
a plurality of rods rotatably supported in contact with outer peripheries of a plurality of disk-shaped members to rotatably hold the disk-shaped members in a state where the plate surfaces of the disk-shaped members face each other,  
wherein a non-rotating member having a substantially disk shape is arranged in a position between the disk-shaped members held by the rods~~member holding means~~.

6. (currently amended) The etching apparatus according to claim 5, further comprising support columns fixed parallel to the rods, wherein the non-rotating member having the substantially disk shape is fixed to the support columns.

7. (cancelled)

8. (currently amended) The etching apparatus according to claim 5, wherein the surface area of the non-rotating member is 95-105% of the surface area of the disk-shaped members.

9. (currently amended) ~~An~~~~A non-rotating member in an~~ etching apparatus comprising:

an etching chamber filled with an etching solution; and

a plurality of rods rotatably supported in contact with the outer peripheries of a plurality of disk-shaped members to rotatably hold the disk-shaped members parallel to one another~~in a state where the plate surfaces of the members face each other,~~

wherein ~~at~~ the non-rotating member having a substantially disk shape is arranged between two~~supported by the rods in place of the~~ disk-shaped members, and

a protruding section for preventing the rotation of the non-rotating member is provided on the outer periphery thereof.

10. (cancelled)

11. (currently amended) The etching apparatus~~non-rotating member~~ according to claim 9, wherein the surface area of the non-rotating member having the substantially disk shape is 95-105% of the surface area of the disk-shaped members.

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12. (currently amended) The etching apparatus~~non-rotating member~~ according to claim 9 or 10, wherein the non-rotating member having the disk shape is made from polypropylene.

13. (previously amended) A method for manufacturing semiconductor wafers comprising a step of etching two or more wafers immersed into an etching solution, while holding the wafers so that the plate surfaces thereof face each other, the etching being while rotating the wafers,

wherein a non-rotating member is disposed between adjacent wafers.